

Contents

1. **Thermal Design Fundamentals**
 - Heat generation in electronic equipment
 - Heat transfer mechanisms: conduction, convection, and radiation
 - Temperature prediction and power dissipation analysis
2. **Electronic Chassis Design**
 - Mechanical configuration
 - Thermal paths and heat flow management
 - Material selection
3. **Conduction Cooling**
 - Printed circuit boards (PCBs)
 - Cold plates and heat spreaders
 - Thermal interface materials
4. **Component Mounting and Cooling**
 - Cooling of semiconductors and integrated circuits
 - Heat sinks
 - Thermal compounds and interface techniques
5. **Natural Convection and Radiation Cooling**
 - Passive cooling methods
 - Convective heat transfer coefficients
 - Radiative heat exchange
6. **Forced-Air Cooling**
 - Fans and blowers
 - Airflow management
 - Pressure drop and cooling system sizing
7. **Thermomechanical Design Considerations**
 - Lead wires and connectors
 - Solder joints
 - Plated-through holes
8. **Thermal Cycling and Vibration Fatigue**
 - Reliability under thermal stress
 - Fatigue mechanisms in electronic assemblies
 - Failure prediction methods
9. **Transient Thermal Analysis**
 - Time-dependent temperature variations
 - Dynamic thermal response
10. **Special Cooling Applications**
 - Harsh operating environments
 - Military, aerospace, and industrial electronics
11. **Cabinet and Rack Cooling**
 - Thermal management of large electronic systems
 - Air distribution strategies
12. **Finite Element Thermal Analysis**
 - Thermal modeling techniques
 - Numerical simulation methods
13. **Environmental Stress Screening (ESS)**
 - Early failure detection
 - Thermal and vibration testing

